

<sup>1</sup> University of Bergamo Department of Engineering and Applied Sciences Dalmine (BG), Italy



<sup>2</sup> University of Pavia, Department of Electrical, Computer and Biomedical Engineering, Pavia, Italy

AVDD

A Time-over-Threshold asynchronous front-end in 28 nm CMOS for the readout of pixel detectors in extreme radiation environments



<sup>3</sup> INFN Sezione di Pavia

<sup>4</sup> INFN Sezione di Bologna

<sup>5</sup> INFN Sezione di Milano



**PRIN PiHEX project** 

L. Gaioni<sup>1,3</sup>, A. Galliani<sup>1,3</sup>, L. Ratti<sup>2,3</sup>, V. Re<sup>1,3</sup>, G. Traversi<sup>1,3</sup>, D. Falchieri<sup>4</sup>, L. Frontini<sup>5</sup> and A. Stabile<sup>5</sup>

TWEPP 2024 - Topical Workshop on Electronics for Particle Physics 2024, 30 September - 4 October 2024, Glasgow, Scotland

## Introduction

Advanced pixel readout chips have been developed by the CERN RD53 collaboration with a 65 nm CMOS technology. These chips have successfully met the performance stringent requirements of the ATLAS and CMS pixel detectors at the High-Luminosity Hadron Large (HL-LHC). Looking Collider towards future developments, the high-energy physics (HEP) microelectronics community is now focusing on the 28 nm CMOS technology. The work presented here addresses the design of analog front-end circuits for future, high-rate pixel detectors based on the 28 nm Specifically, this process. research is part of the PRIN **PiHEX project** (funded by the Italian Ministry of University and Research), which represents a natural continuation of the INFN Falaphel project. Building upon the progress achieved in the latter, in particular in the field of radiation-hard electronics, PiHEX aims to further advance the state-of-the-art in pixel readout technology for highchip luminosity colliders and nextgeneration X-ray imagers.



The analog front-end

- The **VF** reference voltage is provided to the gate of MF to regulate discharge of the preamp feedback capacitance
- A solution has been proposed which makes the architecture robust against process and temperature variations

periphery in-pixel

- **preamplifier** with detector leakage compensation circuit
- preamp **bandwidth** can be limited by loading its output with a 20 fF MoM capacitor ( $C_{BW}$ )
- 5-bit (+ 1 bit sign) threshold **tuning DAC** (TDAC)
- differential input pair loaded with diode connected transistors  $\rightarrow$  single-ended to differential signal conversion (to improve the immunity to interferences)
- standard differential pair with active load
  - + output inverter
- **Time-over-Threshold** counter for A/D conversion of the signal
- **Time-of-Arrival** counter for time-walk measurements



can possibly be distributed along matrix columns (1 every *n* pixels) to compensate for IR drops

## Main simulation results



I \_\_\_\_ current (nA)

Threshold Voltage (mV)

- ENC as a function of detector cap for regular and limited preamp BW (room T and -20°C)
- **Time walk < 15 ns** for the regular BW version
- **ToT** as a function of the input charge (~linear up to 12 ke<sup>-</sup>) in a four corners simulation
- Optimum Threshold dispersion of 0.4 mV (~**16 e r.m.s.**) @ I<sub>DAC</sub> = 200

## Analog macro and chip layout



- Analog island arrangement (2x2 pixels)
- Analog macro size  $\rightarrow$  30 x 17  $\mu$ m<sup>2</sup>
- 8x32 matrix of readout channels (100 x 25  $\mu$ m<sup>2</sup> pixels)
- Shared 8-bit Time of Arrival Counter (640 MHz)
- Shared 5-bit Time-over-Threshold Counter (40 MHz)
- SPI controller
- 1.7 x 1.5 mm<sup>2</sup> prototype chip submitted in July 2024

	<u> </u>		